

ABSTRACT OF THE DISCLOSURE

An insulating substrate (17) includes a surface conductive layer (25) fixedly laminated on a surface of the plate-like semiconductor body (21) via a surface side fixing member (24, 26). The surface side fixing member (24, 26) includes a first fixing portion (26) for fixing one part (25a) of the surface conductive layer (25) located underneath the joint portion (15) of the electrode terminal (14), and a second fixing portion (24) for fixing the other part (25b) of the surface conductive layer (25) which is not located underneath the joint portion (15), and a fixing strength exhibited by the first fixing portion (26) is smaller than that exhibited by the second fixing portion (24).